- Controlled Baseline

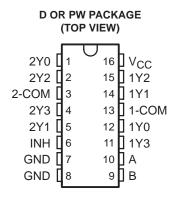
   One Assembly/Test Site, One Fabrication Site
- Extended Temperature Performance of -40°C to 105°C
- Enhanced Diminishing Manufacturing Sources (DMS) Support
- Enhanced Product-Change Notification
- Qualification Pedigree<sup>†</sup>
- Supports Mixed-Mode Voltage Operation on All Ports

#### • Fast Switching

<sup>†</sup> Component qualification in accordance with JEDEC and industry standards to ensure reliable operation over an extended temperature range. This includes, but is not limited to, Highly Accelerated Stress Test (HAST) or biased 85/85, temperature cycle, autoclave or unbiased HAST, electromigration, bond intermetallic life, and mold compound life. Such qualification testing should not be viewed as justifying use of this component beyond specified performance and environmental limits.

#### description/ordering information

- High On-Off Output-Voltage Ratio
- Low Crosstalk Between Switches
- Extremely Low Input Current
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)



This dual 4-channel CMOS analog multiplexer/demultiplexer is designed for 2-V to 5.5-V V<sub>CC</sub> operation.

The SN74LV4052A handles both analog and digital signals. Each channel permits signals with amplitudes up to 5.5 V (peak) to be transmitted in either direction.

Applications include signal gating, chopping, modulation or demodulation (modem), and signal multiplexing for analog-to-digital and digital-to-analog conversion systems.

#### **ORDERING INFORMATION**

TA	PACK	AGE‡	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 105°C	SOIC – D	Tape and reel	SN74LV4052ATDREP	LV4052ATEP
-40 C 10 105 C	TSSOP – PW	Tape and reel	SN74LV4052ATPWREP	L4052EP

‡ Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

## FUNCTION TABLE

	INPUTS		ON
INH	В	Α	CHANNEL
L	L	L	1Y0, 2Y0
L	L	Н	1Y1, 2Y1
L	н	L	1Y2, 2Y2
L	Н	Н	1Y3, 2Y3
Н	Х	Х	None



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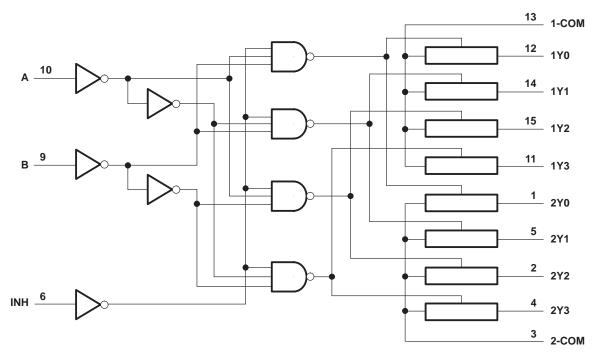
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### logic diagram (positive logic)



#### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)<sup>†</sup>

Supply voltage range, $V_{CC}$ Input voltage range, $V_I$ (see Note 1) Switch I/O voltage range, $V_{IO}$ (see Notes 1 and 2) Input clamp current, $I_{IK}$ ( $V_I < 0$ ) I/O diode current, $I_{IOK}$ ( $V_{IO} < 0$ ) Switch through current, $I_T$ ( $V_{IO} = 0$ to $V_{CC}$ ) Continuous current through $V_{CC}$ or GND Package thermal impedance $0 \times (acc Note 2)$ ; D package	0.5 V to 7.0 V 0.5 V to V <sub>CC</sub> + 0.5 V 20 mA 50 mA ±25 mA ±50 mA
Package thermal impedance, $\theta_{JA}$ (see Note 3): D package	73°C/W
PW package	
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output current ratings are observed. 2. This value is limited to 5.5 V maximum.

3. The package thermal impedance is calculated in accordance with JESD 51-7.



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### recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
VCC	Supply voltage		2†	5.5	V	
		$V_{CC} = 2 V$	1.5			
N/		$V_{CC}$ = 2.3 V to 2.7 V	$V_{CC} \times 0.7$		V	
VIH	High-level input voltage, control inputs	V <sub>CC</sub> = 3 V to 3.6 V	$V_{CC} \times 0.7$		V	
		$V_{CC} = 4.5 V \text{ to } 5.5 V$	$V_{CC} \times 0.7$			
		$V_{CC} = 2 V$		0.5		
	Low-level input voltage, control inputs	$V_{CC}$ = 2.3 V to 2.7 V		$V_{CC} \times 0.3$		
VIL	Low-level input voltage, control inputs	$V_{CC} = 3 V \text{ to } 3.6 V$		$V_{CC} \times 0.3$	V	
		$V_{CC} = 4.5 V \text{ to } 5.5 V$		$V_{CC} \times 0.3$		
VI	Control input voltage		0	5.5	V	
VIO	Input/output voltage		0	VCC	V	
		$V_{CC}$ = 2.3 V to 2.7 V		200		
$\Delta t / \Delta v$	Input transition rise or fall rate	V <sub>CC</sub> = 3 V to 3.6 V		100	ns/V	
		V <sub>CC</sub> = 4.5 V to 5.5 V		20	1	
ТА	Operating free-air temperature		-40	105	°C	

<sup>†</sup> With supply voltages at or near 2 V, the analog switch on-state resistance becomes very nonlinear. It is recommended that only digital signals be transmitted at these low supply voltages.

NOTE 4: All unused inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

I	PARAMETER	TEST CONDITIONS	Vcc	MIN MAX	UNIT
	0		2.3 V	225	
ron	On-state switch resistance	$I_T = 2 \text{ mA}, V_I = V_{CC} \text{ or GND}, V_{INH} = V_{IL}$ , (see Figure 1)	3 V	190	Ω
			4.5 V	100	
	<b>D I I I I</b>		2.3 V	600	
<sup>r</sup> on(p)	Peak on-state resistance	$I_T = 2 \text{ mA}, V_I = V_{CC}$ to GND, $V_{INH} = V_{IL}$	3 V	225	Ω
	Toolotanoo		4.5 V	125	
	Difference in		2.3 V	40	
$\Delta r_{on}$	on-state resistance	$I_T = 2 \text{ mA}, V_I = V_{CC}$ to GND, $V_{INH} = V_{IL}$	3 V	30	Ω
between switches			4.5 V	20	
lj –	Control input current	VI = 5.5 V or GND	0 to 5.5 V	±1	μΑ
IS(off)	Off-state switch leakage current	$V_I = V_{CC}$ and $V_O = GND$ , or $V_I = GND$ and $V_O = V_{CC}$ , $V_{INH} = V_{IH}$ , (see Figure 2)	5.5 V	±1	μA
I <sub>S(on)</sub>	On-state switch leakage current	$V_I = V_{CC}$ or GND, $V_{INH} = V_{IL}$ , (see Figure 3)	5.5 V	±1	μΑ
ICC	Supply current	$V_I = V_{CC} \text{ or } GND$	5.5 V	20	μA



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# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 3.3 V $\pm$ 0.3 V (unless otherwise noted)

	PARAMETER		TEST CONDITIONS	MIN	МАХ	UNIT	
<sup>t</sup> PLH <sup>t</sup> PHL	Propagation delay time	COM or Y	Y or COM	C <sub>L</sub> = 50 pF, (see Figure 4)		12	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Enable delay time	INH	COM or Y	C <sub>L</sub> = 50 pF, (see Figure 5)		25	ns
<sup>t</sup> PHZ <sup>t</sup> PLZ	Disable delay time	INH	COM or Y	C <sub>L</sub> = 50 pF, (see Figure 5)		25	ns

# switching characteristics over recommended operating free-air temperature range, $V_{CC}$ = 5 V $\pm$ 0.5 V (unless otherwise noted)

	PARAMETER	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	МАХ	UNIT
<sup>t</sup> PLH <sup>t</sup> PHL	Propagation delay time	COM or Y	Y or COM	C <sub>L</sub> = 50 pF, (see Figure 4)		8	ns
<sup>t</sup> PZH <sup>t</sup> PZL	Enable delay time	INH	COM or Y	C <sub>L</sub> = 50 pF, (see Figure 5)		18	ns
<sup>t</sup> PHZ <sup>t</sup> PLZ	Disable delay time	INH	COM or Y	C <sub>L</sub> = 50 pF, (see Figure 5)		18	ns

# analog switch characteristics over recommended operating free-air temperature range (unless otherwise noted)

	FROM	то	TES	ST		Τ <sub>4</sub>	λ = 25°C	;		
PARAMETER	(INPUT)	(OUTPUT)	CONDI	TIONS	vcc	MIN	TYP	MAX	UNIT	
			C <sub>L</sub> = 50 pF,	$C_L = 50 \text{ pF},$ $R_L = 600 \Omega,$ $f_{in} = 1 \text{ MHz} \text{ (sine wave)}$			30			
Frequency response (switch on)	COM or Y	Y or COM	_				35		MHz	
				(see Note 5 and Figure 6)			50			
			e_ eep.,		2.3 V		-45			
Crosstalk (between any switches)	COM or Y	Y or COM		$R_L = 600 \Omega$ , f <sub>in</sub> = 1 MHz (sine wave)			-45		dB	
(111 11 11 )			(see Note 6 and	4.5 V		-45				
Crosstalk			C <sub>L</sub> = 50 pF, R <sub>L</sub> = 600 Ω, f <sub>in</sub> = 1 MHz (square wave)		2.3 V		20		mV	
(control input to signal	INH	COM or Y			3 V		35			
output)			(see Figure 8)	are wave)	4.5 V		65			
			CL = 50 pF,		2.3 V		-45			
Feedthrough attenuation (switch off)	COM or Y	Y or COM	R <sub>L</sub> = 600 Ω, f <sub>in</sub> = 1 MHz (sine	wave)	3 V		-45		dB	
(ounter on)			(see Note 6 and		4.5 V		-45			
			$C_{L} = 50 \text{ pF},$ $R_{I} = 10 \text{ k}\Omega,$	V <sub>I</sub> = 2 V <sub>p-p</sub>	2.3 V		0.1			
Sine-wave distortion	COM or Y	Y or COM	f <sub>in</sub> = 1 kHz	VI = 2.5 Vp-p	3 V		0.1		%	
			(sine wave) (see Figure 10)	$V_{I} = 4 V_{p-p}$	4.5 V		0.1			

NOTES: 5. Adjust fin voltage to obtain 0 dBm at output. Increase fin frequency until dB meter reads -3 dB.

6. Adjust fin voltage to obtain 0 dBm at input.



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#### operating characteristics, $T_A = 25^{\circ}C$

	PARAMETER	TEST CO	NDITIONS	TYP	UNIT
Cpd	Power dissipation capacitance	C <sub>L</sub> = 50 pF,	f = 10 MHz	11.8	pF

#### PARAMETER MEASUREMENT INFORMATION

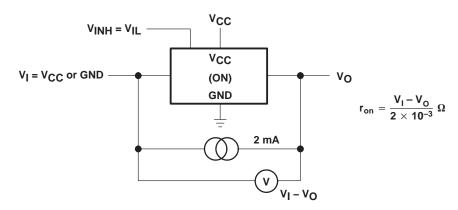
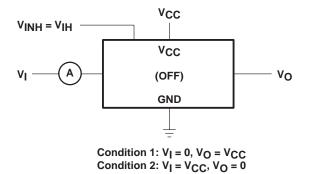


Figure 1. On-State Resistance Test Circuit





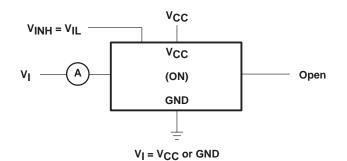
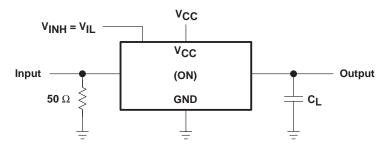


Figure 3. On-State Switch Leakage-Current Test Circuit



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#### PARAMETER MEASUREMENT INFORMATION





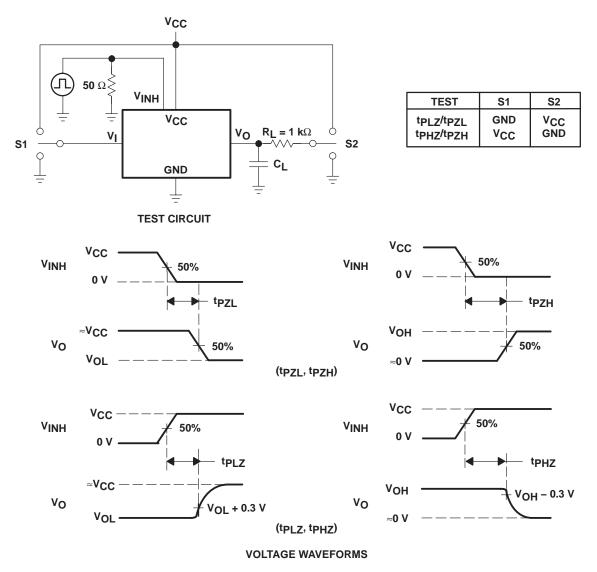
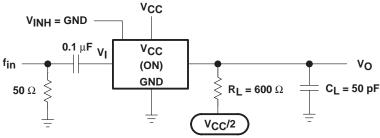


Figure 5. Switching Time ( $t_{PZL}$ ,  $t_{PLZ}$ ,  $t_{PZH}$ ,  $t_{PHZ}$ ), Control to Signal Output



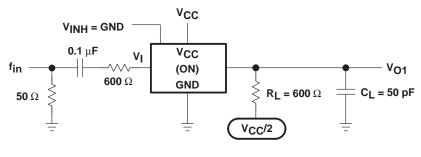
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### PARAMETER MEASUREMENT INFORMATION



NOTE A: fin is a sine wave.

#### Figure 6. Frequency Response (Switch On)



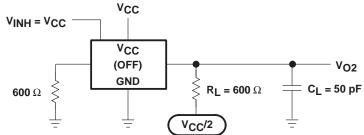


Figure 7. Crosstalk Between Any Two Switches

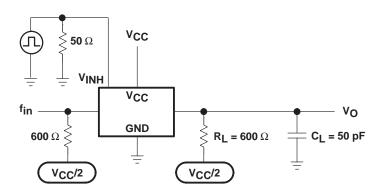
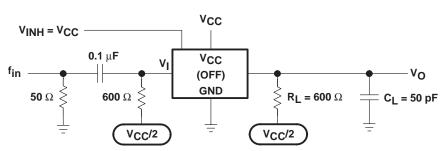


Figure 8. Crosstalk Between Control Input and Switch Output



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#### PARAMETER MEASUREMENT INFORMATION

Figure 9. Feedthrough Attenuation (Switch Off)

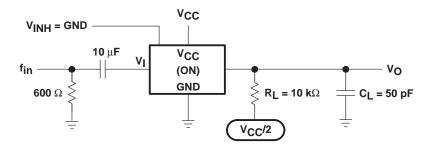


Figure 10. Sine-Wave Distortion



#### PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	e Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
SN74LV4052ATDREP	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74LV4052ATPWREP	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03665-01XE	ACTIVE	TSSOP	PW	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
V62/03665-01YE	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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#### OTHER QUALIFIED VERSIONS OF SN74LV4052A-EP :

Catalog: SN74LV4052A

Automotive: SN74LV4052A-Q1

NOTE: Qualified Version Definitions:

- Catalog TI's standard catalog product
- Automotive Q100 devices qualified for high-reliability automotive applications targeting zero defects

### TAPE AND REEL INFORMATION





## QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



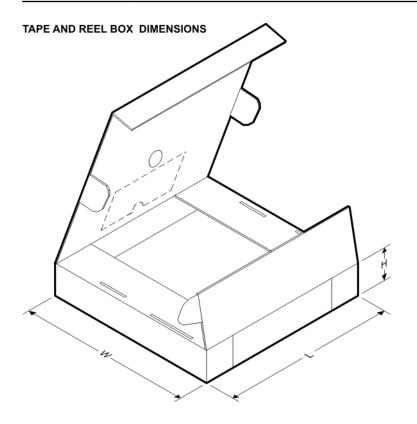
*All dimensions are nominal	

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN74LV4052ATDREP	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1



## PACKAGE MATERIALS INFORMATION

6-Nov-2008



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN74LV4052ATDREP	SOIC	D	16	2500	333.2	345.9	28.6

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